

# **IMPROVED LED PACKAGE**

## **ABSTRACT**

An improved LED package comprises a first stand, a second stand, an  
5 LED chip, an epoxy packaging object, wherein the first stand further  
comprises a concave bowl section, and a first pin is extended from the  
bottom of the first stand, and a second stand is disposed adjacent to the first  
stand and keeps a certain distance from the first stand. The LED chip is  
disposed in the bowl section at the top of the first stand, and the anode of the  
10 LED chip makes use of a conductive metal wire to electrically connect the  
second stand. The epoxy packaging object encapsulates the first stand,  
second stand, and LED chip inside and just leaves the first and second pins  
exposed. A plane perpendicular to the optical path of the light emitted by the  
LED chip is disposed on the top surface of the packaging object, and the top  
15 surface has more than one circular protrusion to achieve the objective of  
enhancing the brightness and uniformity of luminescence.